

S/N 09/901001

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Kathleen Duda
Serial No.:	09/901001	Group Art Unit:	1756
Filed:	July 09, 2001	Docket:	1303.016US1
Title:	COPPER ELECTROLESS DEPOSITION TECHNOLOGY FOR ULSI METALIZATION		

RECEIVED
DEC 01 2003
TCA 1700INFORMATION DISCLOSURE STATEMENT

MS RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. § 1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

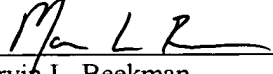
Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

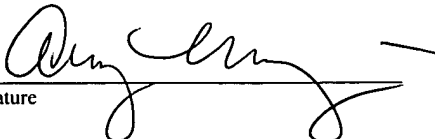
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 373-6960

Date 11-21-03

By 
Marvin L. Beekman
Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21st day of November, 2003.

Amy Moriarty
Name


Signature

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Application Number	09/901001
	Filing Date	July 9, 2001
	First Named Inventor	Ahn, Kie
	Group Art Unit	1756
	Examiner Name	Duda, Kathleen
Sheet 1 of 1	Attorney Docket No: 1303.016US1	



RECEIVED
 DEC 01 2003
 TC 1700

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-010002333	05/31/2001	Huang, Chao-Yuan , et al.	438	637	03/29/1999
	US-5,814,557	09/29/1998	Venkatraman, Ramnath , et al.	438	622	05/20/1996
	US-5,858,877	01/12/1999	Dennison, C. H., et al.	438	700	01/21/1997
	US-5,940,733	08/17/1999	Beinglass, Israel , et al.	438	655	07/29/1997
	US-6,207,558	03/27/2001	Singhvi, Shri , et al.	438	648	10/01/1999
	US-6,342,448	01/29/2002	Lin, J. , et al.	438	687	05/31/2000
	US-6,358,842	03/19/2002	Zhou, Mei-Sheng , et al.	438	633	08/07/2000
	US-6,383,920	05/07/2002	Wang, P. , et al.	438	639	01/10/2001
	US-6,429,120	08/06/2002	Ahn, Kie Y., et al.	438	635	01/18/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
--------------------	---------------------	------------------	-------------------------------------------------	-------	----------	----------------

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		"SiLK* D SEMICONDUCTOR DIELECTRIC RESIN", <u>The DOW Chemical Company, www.silk.dow.com, (Unknown),2</u>	
		"SiLK* J SEMICONDUCTOR DIELECTRIC RESIN", <u>The DOW Company, www.silk.dow.com, (unknown),2</u>	
		EISENBRAUN, E. T., et al., "Selective and Blanket Low-Temperature Copper CVD for Multilevel Metallization in ULSI", <u>Conference Proceedings ULSI-VII, (1992),5 pages</u>	
		KALOYEROS, A. E., et al., "Blanket and Selective Copper CVD from Cu(FOD)2 for Multilvel Metallization", <u>Mat. Res. Soc. Symp. Proc., Vol. 181,(1990),6 pages</u>	
		MARTIN, STEVEN J., "THE INVENTION AND DEVELOPMENT OF A LOW-DIELECTRIC CONSTANT POLYMER FOR THE FABRICATION OF INTEGRATED CIRCUIT INTERCONNECT", <u>Seminar Department of Chemical Engineering, North Carolina State University, (April 9, 2001),1</u>	
		ZHANG, F , et al., "Nanoglass TM E Copper Damascene Processing for Etch, Clean, and CMP", <u>www.electronicmaterials.com/star_center/technical_papers.html, (2001),6</u>	

EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1446)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached